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FAN5362

3MHz, 500mA / 750mA 同步降压稳压器

产品特性

- 3MHz固定频率操作
- 45 μ A典型静态电流
- 1.80 至3.6V 固定输出电压
- 输出电流能力为500mA 或750mA
- 2.7V至5.5V的输入电压范围
- 当 V_{IN} 下降时, 可平滑地进行100%占空比的来回 转换。
- 用于轻载的高效率PFM模式
- 同级最佳的负载瞬态响应
- 同级最佳的效率
- 强制PWM模式和外部时钟同步
- 内部软启动
- 输入欠压闭锁 (UVLO)
- 热关断和过载保护
- 6-焊球WLCSP, 0.4mm 间距或6-引脚2 x 2mm 超薄模塑无铅封装

应用

- SD 闪存电源
- RF收发器电源
- 手机, 智能电话
- 平板电脑、网本®、超级移动电脑
- 3G、LTE、WiMAX™、WiBro®和WiFi®数据卡
- 游戏机, 数码相机/摄像机微模块

说明

FAN5362是500mA或750mA、降压式开关稳压器, 可从2.7V至5.5V的输入电压电源提供固定输出电压。FAN5362将专有架构与同步整流结合在一起, 能够提供96%的峰值效率, 同时在负载电流低至1mA时能够保持90%以上的效率。

当电源电压降至调节设置点或以下时, 该稳压器会无缝地执行100%占空比来回转换操作, 并在电源电压恢复时顺利地恢复整个调节电压, 而不会产生过冲。

该稳压器在3MHz的标称固定频率下运行, 可将外部组件的输出电感值降至1 μ H, 并将输出电容值降至4.7 μ F。PWM调制解调器可与外部频率源保持同步。

在中等负载和轻负载下, 通过脉冲频率调制, 该器件在45 μ A典型静态电流的省电模式下工作。即使在这种低静态电流下, 该部件也能够在大负载摆幅期间展示卓越的瞬态响应。在较高的负载下, 系统会自动切换到固定频率控制, 在3MHz下运行。在关断模式中, 电源电流会降至1 μ A以下, 以便降低功耗。对于需要最低纹波或固定频率的应用, 可以使用MODE引脚来禁用PFM模式。

FAN5362采用6焊球、0.4mm间距、晶圆级芯片尺寸封装(WLCSP)和6引线2 x 2mm超薄塑封无铅封装(UMLP)。

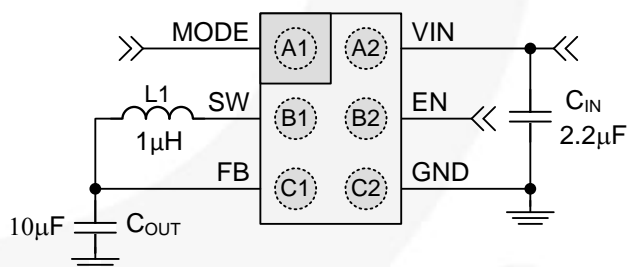


图1. 典型应用

订购信息

| 器件型号 | 输出电压 (V) ¹ | 输出电流 (mA) | 工作温度范围 | 封装 | 包装方法 |
|-----------------------------|-----------------------|-----------|-----------|-----------------------|------|
| FAN5362UC21X ⁽²⁾ | 2.1 | 750 | -40至85° C | WLCSP-6, 0.4 mm 间距 | 卷带 |
| FAN5362UC25X ⁽²⁾ | 2.5 | 500 | | | |
| FAN5362UC27X | 2.7 | 500 | | | |
| FAN5362UC29X | 2.9 | 500 | | | |
| FAN5362UC33X | 3.3 | 500 | | 6-引脚, 2 x 2mm UMLP | |
| FAN5362UMP29X | 2.9 | 500 | | | |
| FAN5362UMP33X | 3.3 | 500 | | | |

注意:

1. 可根据需求提供其他电压。具体请联系飞兆半导体代表。
2. 在此发布的产品非全部产品系列, 其他产品请联系飞兆半导体代表。

表 1 推荐用于图1电路中的组件图1

| 组件 | 说明 | 器件范例 | 典型值 |
|------------------|-------------------------|---------------------------|--------|
| L1 | 1μH, 2012, 190mΩ, 800mA | Murata LQM21PN1R0MCO | 1μH |
| C _{IN} | 2.2μF, 6.3V, X5R, 0402 | Murata GRM155R60J225ME15 | 2.2μF |
| | 2.2μF, 6.3V, X5R, 0603 | GRM188R60J225KE19D | |
| C _{OUT} | 4.7μF, X5R, 0603 | Murata GRM188R60J475M | 4.7μF |
| | 10μF, X5R, 0603 | Murata GRM188R60J106ME47D | 10.0μF |

引脚布局

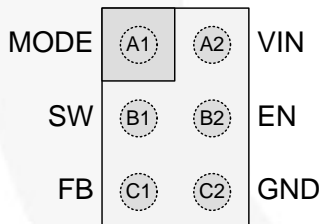


图2. WLCSP, 焊球俯视图

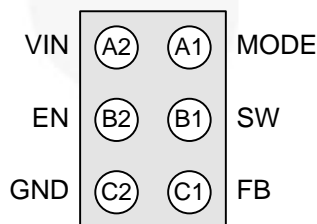


图3. WLCSP, 焊球仰视图

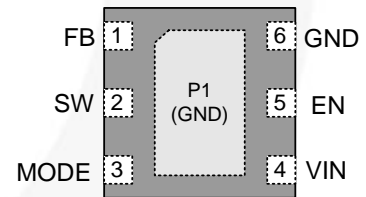


图4. UMLP, 引线朝下

引脚说明

| WLCSP 凸块编号 | UMLP引 脚编号 | 名称 | 说明 |
|---------------|--------------|------|--|
| A1 | 3 | MODE | 该引脚的逻辑1迫使IC保持PWM模式。逻辑0允许芯片在轻载状态时自动切换至PFM。稳压器也将其开关频率同步至该引脚所提供频率的两倍。该引脚不得悬浮。连接高电平时, 如果预计VIN会超过4.5V, 则至少使用1k _Ω 串联电阻。 |
| B1 | 2 | SW | 开关节点。连接至输出电感。 |
| C1 | 1 | FB | 反馈/ V _{OUT} 。连接至外部电压。 |
| C2 | 6 | GND | 接地。电源和IC地。所有信号均以该引脚为参照。 |
| B2 | 5 | EN | 启用。该管脚电压<0.4 V时, 器件为关断模式, 电压>1.2 V时, 器件使能。该引脚不得悬浮。连接高电平时, 如果预计VIN会超过4.5V, 则至少使用1k _Ω 串联电阻。 |
| A2 | 4 | VIN | 输入电压。连接至输入电源。 |

绝对最大额定值

应力超过绝对最大额定值，可能会损坏设备。在超出推荐的工作条件的情况下，该器件可能无法正常运行或操作，且不建议让器件在这些条件下长期工作。此外，过度暴露在高于推荐的工作条件下，会影响器件的可靠性。绝对最大额定值仅是额定应力值。

| 符号 | 参数 | 最小值 | 最大值 | 单位 |
|------------|-------------|--------------------|----------------------|----|
| V_{IN} | 输入电压 | -0.3 | 6.5 | V |
| V_{SW} | SW引脚上的电压 | -0.3 | $V_{IN} + 0.3^{(3)}$ | V |
| V_{CTRL} | EN与MODE引脚电压 | -0.3 | $V_{IN} + 0.3^{(3)}$ | V |
| V_{FB} | FB引脚 | -0.3 | 4 | V |
| ESD | 静电放电防护等级 | 人体模型满足JESD22-A114 | 3.0 | kV |
| | | 充电器件模型 JESD22-C101 | 1.5 | |
| T_J | 结温 | -40 | +150 | °C |
| T_{STG} | 存储温度 | -65 | +150 | °C |
| T_L | 引脚焊接温度，10秒 | | +260 | °C |

注意：

3. 选取6.5V与 $V_{IN}+0.3$ 中的较小值。

推荐工作条件

推荐的操作条件定义了器件的真实工作条件。指定推荐的工作条件，以确保设备的最佳性能达到数据表中的规格。飞兆半导体建议不要超过推荐工作条件，也不能按照绝对最大额定值进行设计。

| 符号 | 参数 | 最小值 | 典型值 | 最大值 | 单位 |
|-----------|-----------------------------|--------------------|-----|------|----|
| V_{CC} | 电源电压范围 | 2.7 ⁽⁴⁾ | | 5.5 | V |
| I_{OUT} | 2.1V的输出电流 | 0 | | 750 | mA |
| | 2.5V, 2.7V, 2.9V, 3.3V的输出电流 | 0 | | 500 | |
| L | 电感 | | 1 | | μH |
| C_{IN} | 输入电容 | | 2.2 | | μF |
| C_{OUT} | 输出电容 | | 10 | 24 | μF |
| T_A | 操作环境温度 | -40 | | +85 | °C |
| T_J | 工作结温 | -40 | | +125 | °C |

注意：

4. V_{IN} 最小值= $V_{OUT} + 200mV$ 或2.7V中的较大值。

热性能

结-环境之间热阻与具体应用和电路板布局有关。该数据由1s2p四层板测得，符合JESD51-JEDEC标准。特别注意的是，不要超过给定环境温度 T_A 时的结温 $T_J(max)$ 。

| 符号 | 参数 | 典型值 | 单位 |
|---------------|----------|-------|-----|
| θ_{JA} | 结-环境之间热阻 | WLSQP | 150 |
| | | UMLP | 49 |

电气特性

若没有其它说明，测得最大值和最小值的条件为 $V_{IN} = V_{EN} = 2.7V$ 至 $5.5V$ ， $V_{MODE} = 0V$ （AUTO模式）， $T_A = -40^\circ C$ 至 $+85^\circ C$ ；图1电路。典型值的测量条件为 $T_A = 25^\circ C$ ， $V_{IN} = V_{EN} = 3.6V$ ， $V_{MODE} = 0V$ ， $C_{OUT} = 10\mu F$ 。

| 符号 | 参数 | 工作条件 | 最小值 | 典型值 | 最大值 | 单位 | |
|---|-------------------------|--|---|----------------|-------|----------------|----|
| 电源 | | | | | | | |
| I _q | 静态电流 | 无负载，无开关， $V_{IN} > 3V$ | | 45 | 75 | μA | |
| | | PWM 模式 | | 5 | | mA | |
| I _(SD) | 停机电源电流 | EN = GND | | 0.05 | 1.00 | μA | |
| V _{UVLO} | 欠压闭锁阈值 | V _{IN} 升 | | 2.5 | 2.6 | V | |
| V _{UVHYST} | 欠压锁定滞环宽度 | | | 175 | | mV | |
| V _(ENH) | 启用输入电压高电平 | | 1.05 | | | V | |
| V _(ENL) | 启用输入电压低电平 | | | | 0.4 | V | |
| I _(EN) | 启用输入漏电流 | EN至V _{IN} 或GND | | 0.01 | 1.00 | μA | |
| V _(MH) | MODE输入电压高电平 | | 1.05 | | | V | |
| V _(ML) | MODE输入电压低电平 | | | | 0.4 | V | |
| I _(M) | MODE输入漏电流 | MODE至V _{IN} 或GND | | 0.01 | 1.00 | μA | |
| 开关和同步 | | | | | | | |
| f _{SW} | 开关频率 ⁽⁵⁾ | V _{IN} = 3.6V, T _A = 25° C | 2.7 | 3.0 | 3.3 | MHz | |
| f _{SYNC} | MODE同步范围 ⁽⁵⁾ | MODE输入时的方波 | 1.3 | 1.5 | 1.7 | MHz | |
| 调节 | | | | | | | |
| V _O | 输出电压精度 | 2.10 V | I _{LOAD} = 0至750 mA | 2.037 (-3%) | 2.100 | 2.163 (+3%) | V |
| | | 2.50 V | I _{LOAD} = 0至400 mA, V _{IN} ≥ V _{OUT} + 200 mV | 2.375 (-5%) | 2.500 | 2.575 (+3%) | |
| | | | I _{LOAD} = 0至500 mA, V _{IN} ≥ V _{OUT} + 300 mV | 2.425 (-3%) | 2.500 | 2.575 (+3%) | |
| | | 2.70V、2.90V、 3.30V | I _{LOAD} = 0至400 mA, V _{IN} ≥ V _{OUT} + 150 mV | -5% | | +3% | |
| I _{LOAD} = 0至500 mA, V _{IN} ≥ V _{OUT} + 300 mV | -3% | | | +3% | | | |
| t _{SS} | 软启动 | 来自EN上升沿 | | 180 | 300 | μs | |
| 输出驱动器 | | | | | | | |
| R _{DS(on)} | PMOS 导通电阻 | V _{IN} = V _{GS} = 3.6V | | 330 | | m \square | |
| | NMOS 导通电阻 | V _{IN} = V _{GS} = 3.6V | | 300 | | m \square | |
| I _{LIM(OL)} | PMOS峰值限流 ⁽⁵⁾ | V _{OUT} = 2.1V | | 1375 | | mA | |
| | | V _{OUT} = 2.5V, 2.7V, 2.9V, 3.3V | | 800 | 1000 | 1150 | mA |
| T _{TSD} | 热关断 | | | 150 | | ° C | |
| T _{HYS} | 热关闭滞环宽度 | | | 15 | | ° C | |

说明：

- 受限于t_{OFF}最小值（参见图 图8的典型操作性能）。
- 电气特性表所示为开环数据。参考操作说明和典型特性，可了解闭环的相关数据。

典型特性

若没有特别说明, $V_{IN}=V_{EN}=3.6V$, $V_{MODE}=0$ (AUTO), $V_{OUT}=2.9V$, $C_{OUT}=10\mu F$, 且 $T_A=25^\circ C$ 。

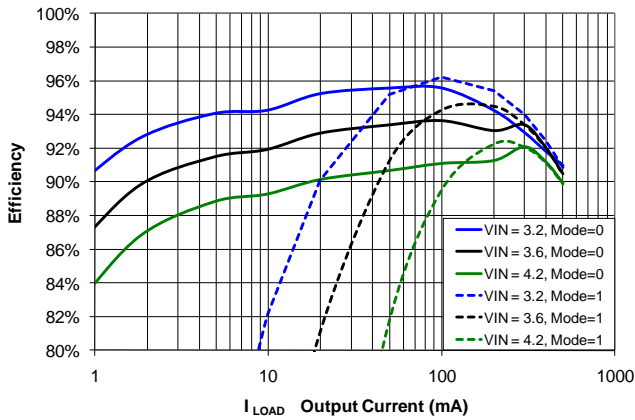


图5. 效率vs负载电流和输入电源的关系

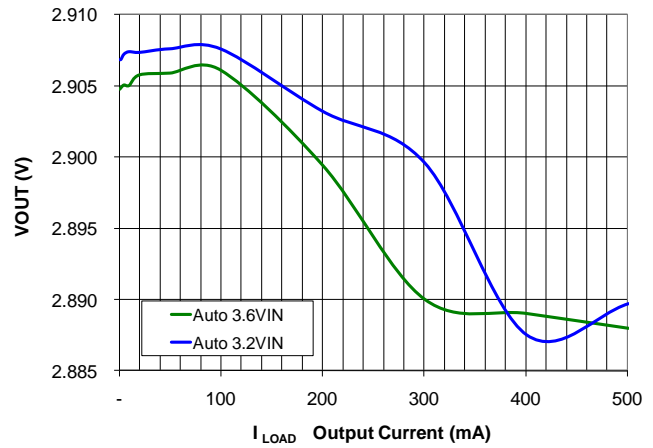


图6. 负载调节

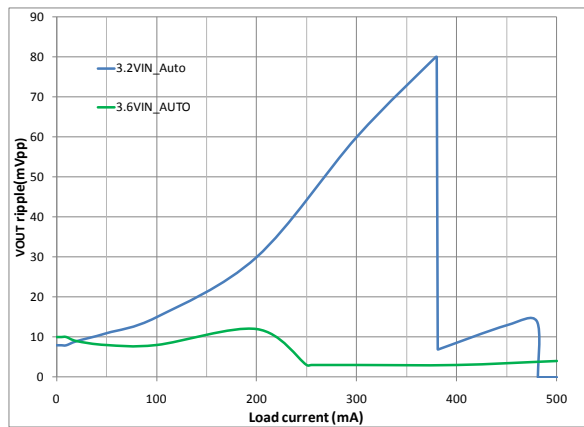


图7. 纹波

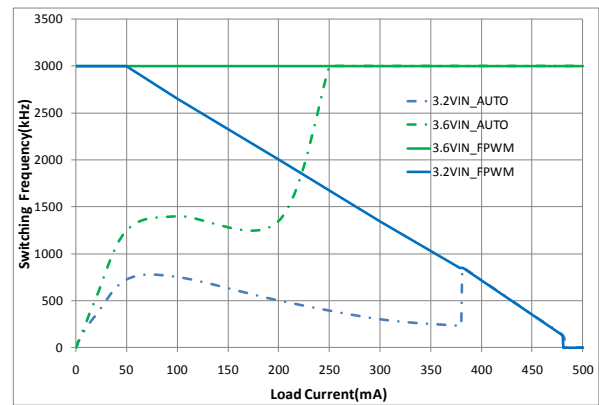


图8. 降低开关频率的 t_{OFF} (MIN) 效应

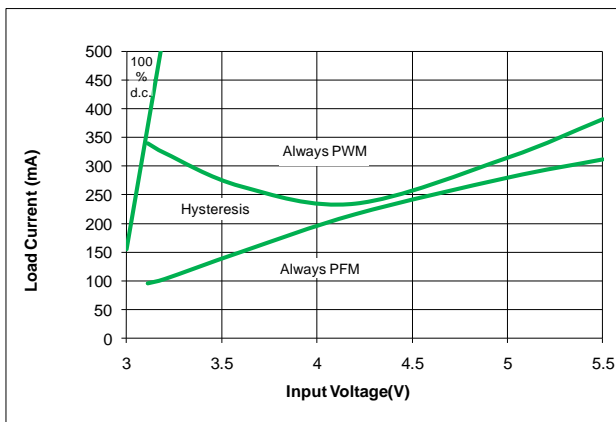


图9. PFM / pwm 边界

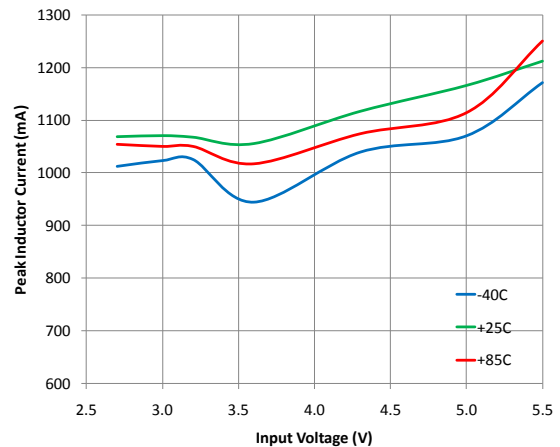


图10. 峰值感应电流

典型特性

若没有特别说明, $V_{IN}=V_{EN}=3.6\text{V}$, $V_{MODE}=0$ (AUTO), $V_{OUT}=2.9\text{V}$, $C_{OUT}=10\mu\text{F}$, 且 $T_A=25^\circ\text{C}$ 。

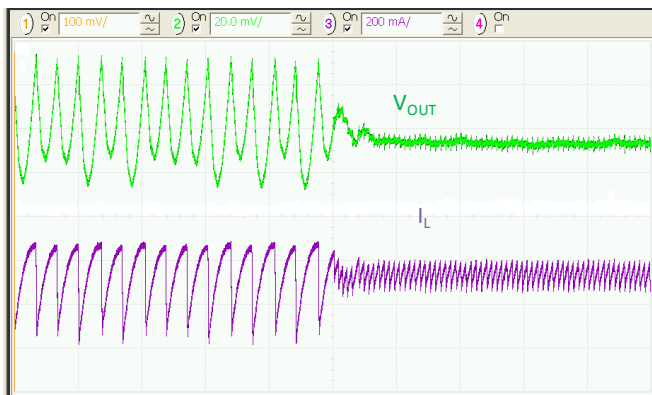


图11. $V_{IN}=3.2\text{V}$, $10\mu\text{s/div}$, PFM转换至PWM

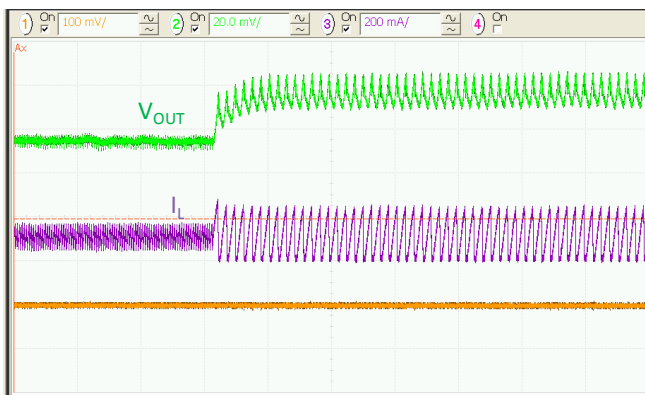


图12. $V_{IN}=3.2\text{V}$, $10\mu\text{s/div}$, PWM转换至PFM

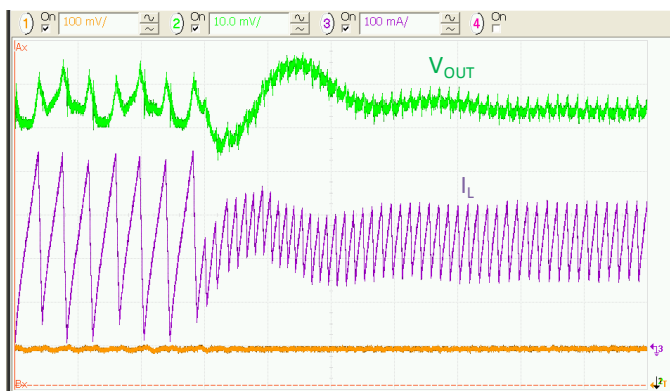


图13. $V_{IN}=3.6\text{V}$, $2\mu\text{s/div}$, PFM转换至PWM



图14. $V_{IN}=3.6\text{V}$, $2\mu\text{s/div}$, PWM转换至PFM

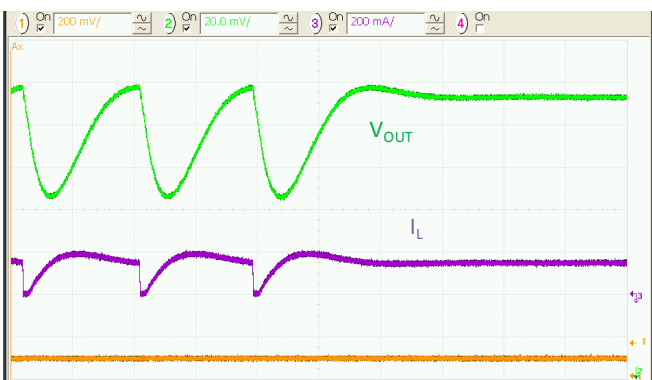


图15. $V_{IN}=3.2\text{V}$, $5\mu\text{s/div}$, 常规开关至100%占空比转换

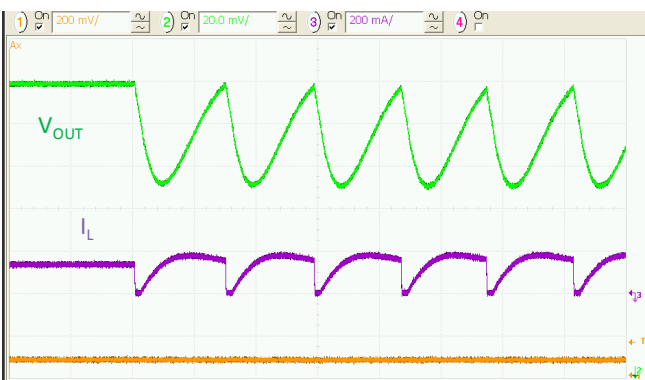


图16. $V_{IN}=3.2\text{V}$, $5\mu\text{s/div}$, 100%占空比至常规开关转换

典型特性

若没有特别说明, $V_{IN}=V_{EN}=3.6V$, $V_{MODE}=0$ (AUTO), $V_{OUT}=2.9V$, $C_{OUT}=10\mu F$, 且 $T_A=25^\circ C$ 。

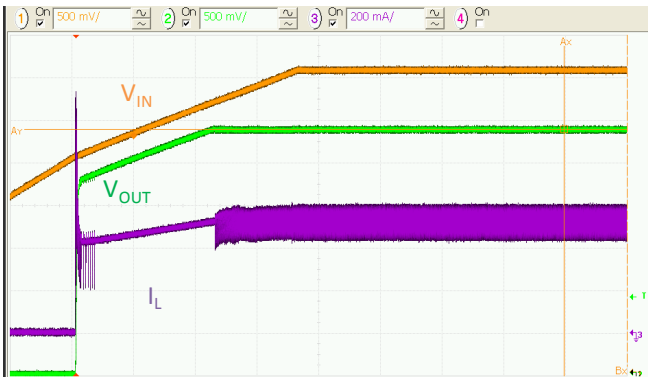


图17. 500mA负载, 1ms/div, 启动变化 $V_{IN}=V_{EN}$



图18. 500 mA 负载, 50 μs /div, 启动和关断 V_{EN}

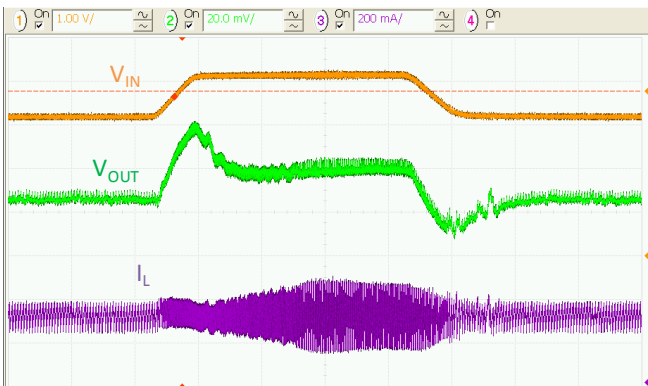


图19. 线路瞬态, $V_{IN}=3.2V$ 至 $4.2V$, 300 mA负载, $t_{RISE}=t_{FALL}=10\mu s$, 20 μs /div

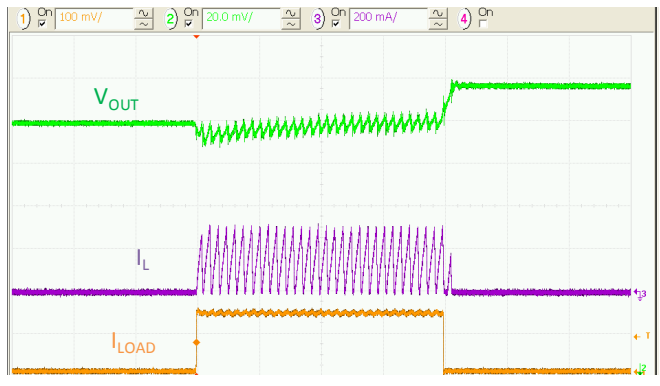


图20. 负载瞬态, 0 mA 至150 mA, $V_{IN}=3.6V$, $t_{RISE}=t_{FALL}=100$ ns, 5 μs /div.

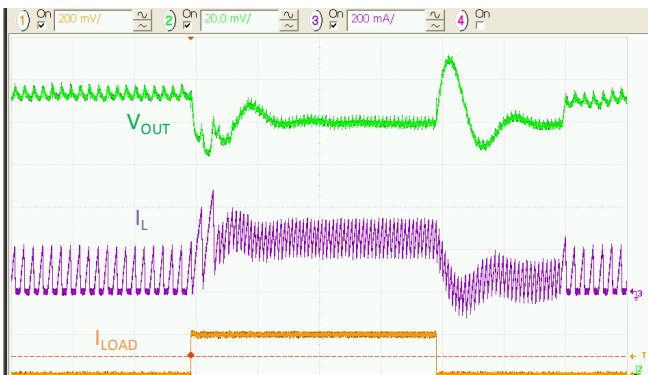


图21. 负载瞬态, 50 mA至250 mA, $V_{IN}=3.6V$, $t_{RISE}=t_{FALL}=100$ ns, 5 μs /div.



图22. 负载瞬态, 150 mA 至400 mA, $V_{IN}=3.6V$, $t_{RISE}=t_{FALL}=100$ ns, 5 μs /div.

典型特性

若没有特别说明, $V_{IN}=V_{EN}=3.6V$, $V_{MODE}=0$ (AUTO), $V_{OUT}=2.9V$, $C_{OUT}=10\mu F$, 且 $T_A=25^\circ C$ 。



图23. 负载瞬态, 50 mA 至250 mA, $V_{IN}=3V$, $t_{RISE}=t_{FALL}=100ns$, $5\mu s/div$ 。



图24. 负载瞬态, 150 mA至400 mA, $V_{IN}=3V$, $t_{RISE}=t_{FALL}=100ns$, $5\mu s/div$ 。

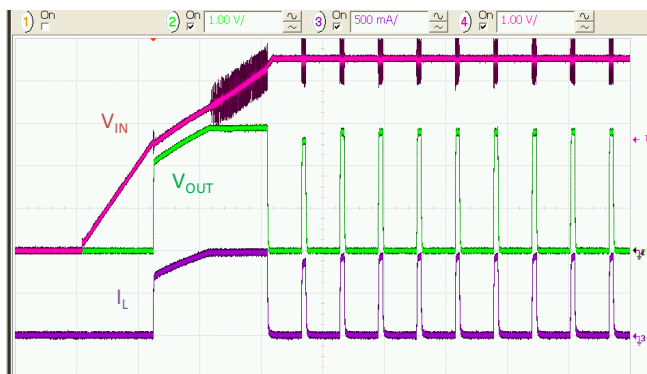


图25. 启动变化 $V_{IN}=V_{EN}$ 至过载, 负载 $\approx 3A$, $5ms/div$ 。

工作说明

FAN5362是一款额定电流为500mA或750mA的降压开关稳压器，可将5.5V以下的输入电源电压转换为固定的输出电压。FAN5362采用独特的同步整流器结构，可在负载电流低至1mA时仍保持90%的效率，实现96%的峰值效率。稳压器在名义固定频率3MHz下工作，可降低外部组件值，输出电感降至1μH，输出电容降至4.7μF。使用单脉冲PFM模式，在轻载时可保持高效。

控制模式

FAN5362使用独特的非线性、固定频率PWM调制器，实现快速负载瞬态响应，同时在较宽的操作条件下保持恒定的开关频率。稳压器性能独立于输出电容ESR，可使用陶瓷输出电容。尽管这类操作通常会导致开关频率随输入电压和负载电流发生变化，但内部频率环可在较大的输入电压和负载电流范围内保持开关频率的稳定。

若为极轻载情况，FAN5362在断续电流（DCM）单脉冲PFM模式下操作，与其他PFM结构相比，可产生较低的输出纹波。DCM和CCM模式下转换时，VOUT的扰动小于18mV，PWM和PFM间可无缝转换。

利用独特的瞬态响应特性，控制器在负载极小，极低静态电流（45μA）下仍可保持高效，在对输出调节严格要求的应用中保持快速的瞬态响应。

100%占空比操作

当VIN接近VOUT时，稳压器提高占空比，直至达到100%。占空比接近100%时，控制电路令关断时间最小值（tOFF(MIN)）约35ns，致使开关频率降低。达到100%占空比时，VIN和VOUT之间总电阻可决定VOUT与VIN的跌落电压（VDROPOUT）。

$$V_{\text{DROPOUT}} = I_{\text{LOAD}} \cdot (\text{PMOS } R_{\text{DS(ON)}} + \text{DCR}_L) \quad (1)$$

若要计算最坏情况下的VDROPOUT，使用图所示高温情况下的PMOS RDS(ON)图6最大值进行计算。

启用软启动

EN引脚为低电平，IC关断且该部分吸引极少的电流。此外，关断时，FB通过230Ω路径主动放电接地。EN升过其阈值电压可激活该部件并开始软启动循环。软启动期间，使用指数RC波形改变内部参考电压，防止输出电压超调。电流限值可将软启动期间的冲击电流降到最低。

软启动期间禁止同步整流器，从而IC可开始预充电负载。

如果在启动期间负载过大，或使用过高的COUT，则IC无法启动。因为有电流限值错误响应，该响应是用来保护IC在软启动期间免受过大电流冲击。

软启动期间用来对COUT充电的电流通常称之为“位移电流”，计算式如下：

$$I_{\text{DISP}} = C_{\text{OUT}} \cdot \frac{dV}{dt} \quad (2)$$

其中 $\frac{dV}{dt}$ 指软启动压摆率。

为防止软启动期间关断，必须满足下列条件：

$$I_{\text{DISP}} + I_{\text{LOAD}} < I_{\text{MAX(DC)}} \quad (3)$$

式中 I_{MAX(DC)} 为IC可支持的最大负载电流（500mA或750mA）。

MODE引脚

该引脚的逻辑1迫使IC保持PWM模式。逻辑0允许芯片在轻载状态时自动切换至PFM。如果MODE引脚切换，转换电路可将其开关频率同步至MODE引脚（fMODE）频率的四倍。

启动时，MODE引脚必须保持低电平或高电平至少10μs，以确保转换电路不会尝试与该引脚同步。

欠压锁定

EN高电平时，欠压锁定令部件无法操作，直至电源电压升高到足以正常操作的水平。从而保证在启动或关机期间避免出现误操作。

电流限制

输出电路中的大负载或短路会导致电感中的电流增大，直至达到高端开关的最大电流阈值。达到该值后，高端开关关闭，以避免因电流过大造成损坏。电流限制中若有16个连续的PWM循环，将使调节器关闭并停止大约2900μs，然后尝试重新启动。

出现短路时，软启动电路在240μs时尝试重新启动，占空比小于10%，为短路线路提供电流。

在电气特性表中，闭环峰值电流限值ILIM(PK)，与开环测试电流限值ILIM(OL)不同。这主要是由于IC电流限制比较器的传输延迟造成的。

热关断

由于负载过大或环境温度过高造成死区温度升高时，输出开关电路将禁用，直至死区温度充分降低后方可启用。结温即启动热关闭的温度通常为150°C，滞环为20°C。

最小关断时间对开关频率的影响

$t_{OFF(MIN)}$ 为35ns。这使得FAN5362可提供的最大值 $\frac{V_{OUT}}{V_{IN}}$ 受到限制，或者使得该器件在低 V_{IN} 下可提供的最大输出电压受到限制，同时在PWM模式下保持固定开关频率。

V_{IN} 处于低电平时，只要 $\frac{V_{OUT}}{V_{IN}} \leq 1 - t_{OFF(MIN)} \cdot f_{SW} \approx 0.7$

若稳压器无法在3MHz时提供足够大的占空比来进行调节，则开关频率将跌落。额定负载电流时，若 V_{IN} 低于3.3V 就会出现这种情况。

开关频率的计算式如下：

$$f_{SW} = \min\left(\frac{1}{t_{SW(MAX)}}, 3\text{MHz}\right) \quad (4)$$

其中：

$$t_{SW(MAX)} = 35\text{ns} \cdot \left(1 + \frac{V_{OUT} + I_{OUT} \cdot R_{OFF}}{V_{IN} - I_{OUT} \cdot R_{ON} - V_{OUT}}\right) \quad (5)$$

其中：

$$R_{OFF} = R_{DSON_N} + DCR_L$$

$$R_{ON} = R_{DSON_P} + DCR_L$$

应用信息

选择电感

选择的输出电感器必须能提供所需的电感和应用所需的能量处理能力。

电感值将影响到电流限值的平均值，PWM-至-PFM 转换点，输出电压纹波以及效率。

稳压器的纹波电流 (ΔI) 为：

$$\Delta I \approx \frac{V_{OUT}}{V_{IN}} \cdot \left(\frac{V_{IN} - V_{OUT}}{L \cdot f_{SW}}\right) \quad (6)$$

最大平均负载电流 $I_{MAX(Load)}$ 取决于峰值电流限值 $I_{LIM(PK)}$ 和纹波电流：

$$I_{MAX(Load)} = I_{LIM(PK)} - \frac{\Delta I}{2} \quad (7)$$

优化的FAN5362以 $L=1\mu\text{H}$ 进行操作，但在电感上限1.5 μH （标称值）与下限470 nH的范围内都可保持稳定性能。电感器应保持其峰值 $I_{LIM(PK)}$ 的80%。若无法保持，则降低IC输送的直流电流。

电感DCR和电感值对效率会产生影响。降低特定尺寸的电感值会缩小DCR；但由于 ΔI 增大，且RMS电流增大，核心和表层的效应损耗也将增大。

$$I_{RMS} = \sqrt{I_{OUT(DC)}^2 + \frac{\Delta I^2}{12}} \quad (8)$$

增大的RMS电流将提高损耗，通过IC MOSFET的 $R_{DS(ON)}$ 和电感ESR。

增大电感值可降低RMS电流，但会影响瞬态响应。对于一定尺寸的电感器，若提高电感则将其饱和电流降低，DCR增大。

额定电感电流

FAN5362 的电流限制电路允许在最坏情况下让1.25A的峰值电流通过 L1。若负载可连续吸收该电流，电感则可以保持该电流，或进入故障安全状态。

输出电容

尽管在0402封装尺寸中使用4.7 μF 电容器，但仍推荐使用0603电容器，因为0402的电容量会严重降低直流电压的偏压。

提高 C_{OUT} 不影响环路稳定性，且能够降低输出电压纹波或提高瞬态响应。输出电压纹波 ΔV_{OUT} 为：

$$\Delta V_{OUT} = \Delta I \cdot \left(\frac{1}{8 \cdot C_{OUT} \cdot f_{SW}} + ESR\right) \quad (9)$$

若使用的 C_{OUT} 值大于24F，调节器将无法启动。请查看启用和软启动章节，了解更多信息。

输入电容

2.2 μF 陶瓷输入电容器应尽可能靠近 V_{IN} 引脚和GND放置，将寄生电感降到最低。如果用来给IC供电的线路较长，则应在 C_{IN} 和电源引脚之间添加一个“bulk”电容（电解电容或钽电容），从而降低电感和电容引脚和 C_{IN} 之间的振荡。

PCB布局指南

仅三个外部组件：电感器，输入电容和输出电容。对于包括FAN5362在内的任何一个降压开关IC，重点在于要将一个低ESR的输入电容靠近IC放置，如图26。所示。输入电容可确保实现输入去耦，从而降低输出端的噪声，并确保IC的控制部分不会因过多的噪声出现错误。可降低开关循环抖动，并确保良好的总体特性。重点在于，将CIN 和COUT的GND尽可能靠近C2端子。电感的放置有一定灵活性，可距离IC 较远放置，此时应放在COUT 端子附近。

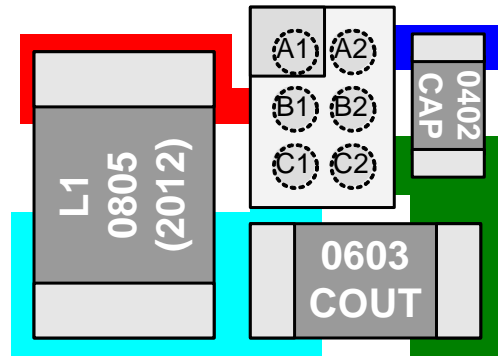
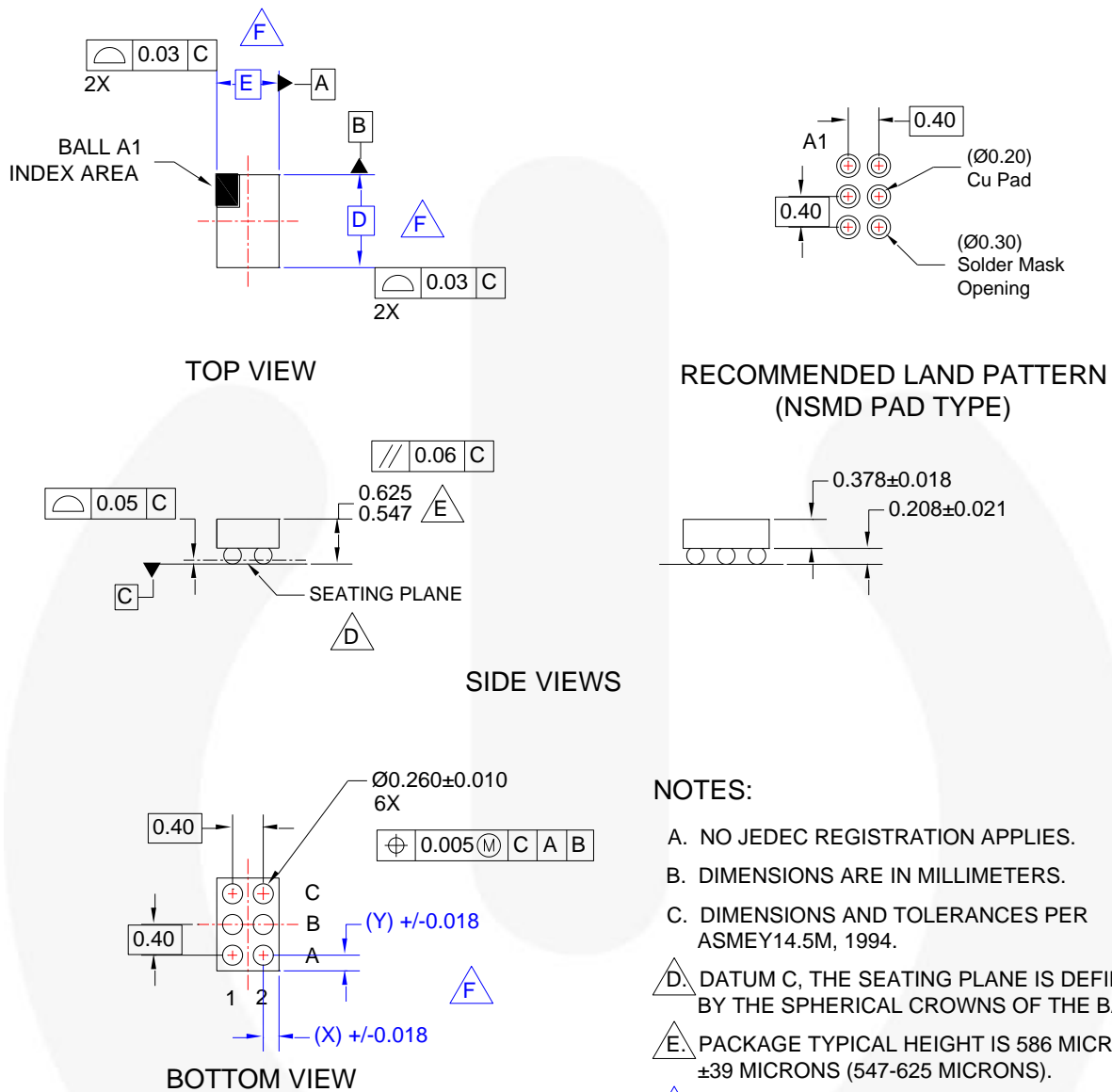


图26。 PCB推荐布局

物理尺寸测试



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASMEY14.5M, 1994.
- D. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE TYPICAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- G. DRAWING FILENAME: UC006ACrev4.

图27. 晶圆级芯片封装间距

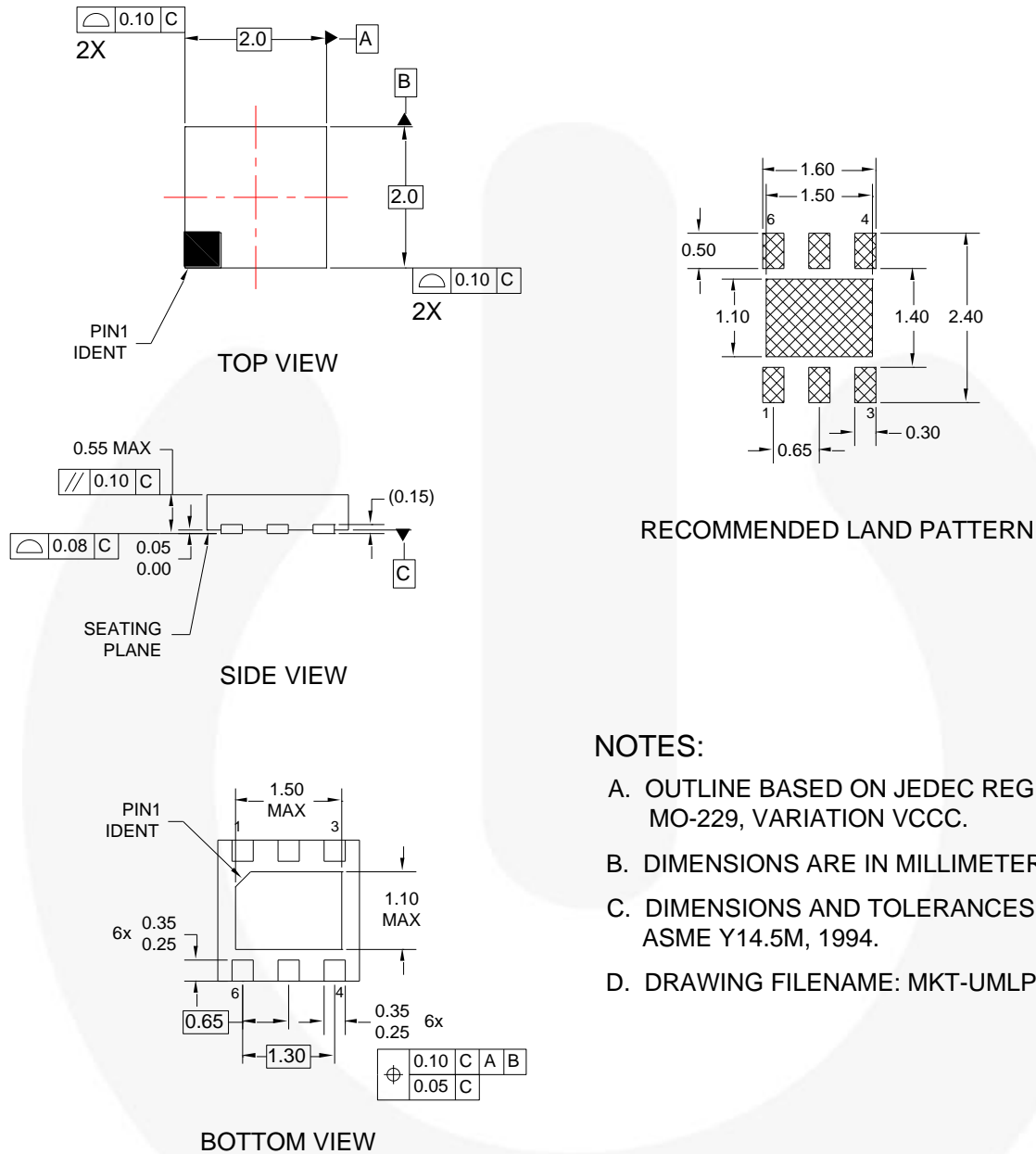
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| 产品 | D | E | X | Y |
|------------|----------------|----------------|-------|-------|
| FAN5362UCX | 1.310 +/-0.030 | 0.960 +/-0.030 | 0.280 | 0.255 |

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物理尺寸测试



NOTES:

- A. OUTLINE BASED ON JEDEC REGISTRATION MO-229, VARIATION VCCC.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. DRAWING FILENAME: MKT-UMLP06Crev1

图28. 6-引脚, 2 x 2mm, 超薄模塑无铅封装 (UMLP)

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